

LN2162C68TR

Surface Mounting Chip LED

GW Bi-Color Type

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

- Pure Green

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	45	mW
Forward current	I_F	15	mA
Pulse forward current *	I_{FP}	60	mA
Reverse voltage	V_R	3	V
Operating ambient temperature	T_{opr}	-25 to +80	$^\circ\text{C}$
Storage temperature	T_{stg}	-30 to +85	$^\circ\text{C}$

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Lighting Color / Lens Color

- Pure Green / Clear
- Orange / Clear

- Orange

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	45	mW
Forward current	I_F	15	mA
Pulse forward current *	I_{FP}	60	mA
Reverse voltage	V_R	3	V
Operating ambient temperature	T_{opr}	-25 to +80	$^\circ\text{C}$
Storage temperature	T_{stg}	-30 to +85	$^\circ\text{C}$

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Electro-Optical Characteristics $T_a = 25^\circ\text{C}$

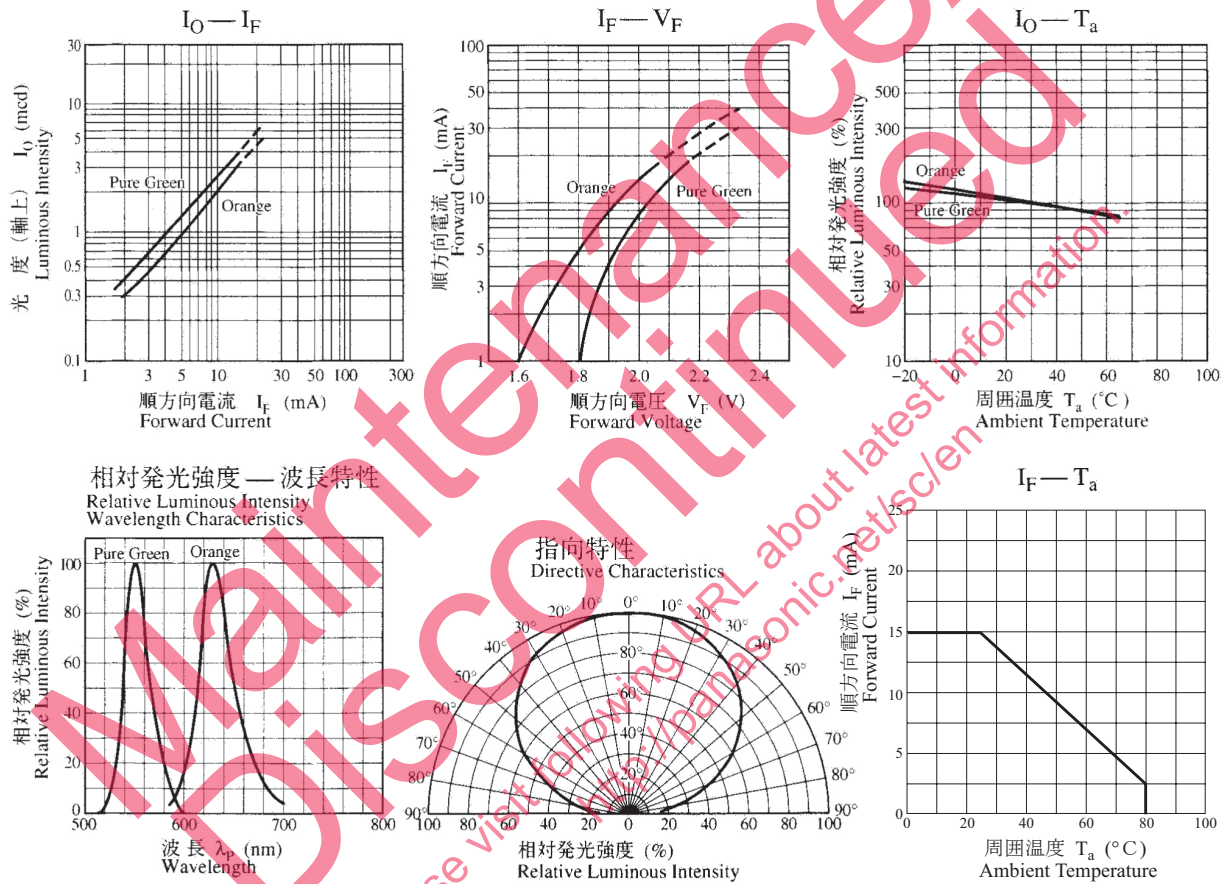
- Pure Green

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	I_O		1.2	2.5		md
Forward current	I_F			10		mA
Forward voltage	V_F	$I_F = 10\text{ mA}$		2.05	2.8	V
Peak emission wavelength	λ_p	$I_F = 10\text{ mA}$		555		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10\text{ mA}$		25		nm
Reverse current	I_R	$V_R = 3\text{ V}$			10	μA

■ Electro-Optical Characteristics (Continued) $T_a = 25^\circ\text{C}$

• Orange

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	I_O		0.8	2.1		mcd
Forward current	I_F			10		mA
Forward voltage	V_F	$I_F = 10\text{ mA}$		1.95	2.8	V
Peak emission wavelength	λ_p	$I_F = 10\text{ mA}$		630		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10\text{ mA}$		40		nm
Reverse current	I_R	$V_R = 3\text{ V}$			10	μA



Technical drawing of a rectangular component with four mounting tabs. The drawing includes top and side views with dimensions in millimeters.

Top View Dimensions:

- Overall width: 2.7 ± 0.2
- Overall height: 3.4 ± 0.2
- Distance between centers of left and right tabs: (2.1)
- Distance between centers of top and bottom tabs: (2.7)
- Chamfered corner radius: $C0.3$
- Chamfer width: 0.8 Max

Side View Dimensions:

- Overall height: 1.8 Max
- Base thickness: 0.15
- Top thickness: 0.65 ± 0.2
- Distance between centers of left and right tabs: 4.3 ± 0.3
- Distance between centers of top and bottom tabs: 1.5 ± 0.2
- Chamfered corner radius: $C0.5$
- Chamfer width: 0.8 Max

Legend:

- 1 ——— 2 Green
- 3 ——— 4 Orange

1, 3: Anode
2, 4: Cathode

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